Alumbaa I	1 1:4-	Casab Tad	DB	Time stamp
L Number	Hits	Search Text	JPO	Time stamp 2003/08/13 14:11
3	1	kohashi.in.		1
4	114	kohashi	JPO;	2003/08/13 14:11
i _	_		DERWENT	0000/00/40 45:50
5	7	kohashi and semiconductor	JPO;	2003/08/13 15:59
_			DERWENT	
6	17887	die near3 bond\$3	USPAT;	2003/08/13 16:00
			US-PGPUB;	
			EPO; JPO;	
7			DERWENT	000000000000000000000000000000000000000
	558	(die near3 bond\$3) and semiconductor near3 laser	USPAT;	2003/08/13 16:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
9	151	(die near3 bond\$3) and semiconductor near3 laser near3 chip	USPAT;	2003/08/13 16:57
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
	404	braz\$3 near3 epoxy	USPAT;	2003/08/13 16:58
			US-PGPUB;	
			EPO; JPO;	
10			DERWENT	
	123	braz\$3 near3 epoxy and fill\$3 and conduct\$3	USPAT;	2003/08/13 16:59
			US-PGPUB;	
			EPO; JPO;	
	_		DERWENT	
	8	(braz\$3 near3 epoxy) and fill\$3 and conduct\$3 and (die near3	USPAT;	2003/08/13 17:06
		bond\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT	0000/00/40 47 45
12	23	(die near3 bond\$3) and (epoxy near3 resin) and (conduct\$3	USPAT;	2003/08/13 17:15
		near3 fill\$3) and (semiconductor near3 laser)	US-PGPUB;	
			EPO; JPO;	
40	•	("	DERWENT	0000/00/40 47 00
13	3	(die near3 bond\$3) and (epoxy near3 resin) and (conduct\$3	USPAT;	2003/08/13 17:08
		near3 fill\$3) and (semiconductor near3 laser near3 chip)	US-PGPUB;	
			EPO; JPO;	
44	404	(dia	DERWENT	0000/00/40 47:45
14	121	(die near3 bond\$3) and (epoxy near3 resin) and (conduct\$3	USPAT;	2003/08/13 17:15
		near3 fill\$3) and chip and laser	US-PGPUB;	
			EPO; JPO; DERWENT	
16	2	(/dia near) hand(2) and (analy near) regin) and (conduct(2)		2002/00/12 17:16
16	2	((die near3 bond\$3) and (epoxy near3 resin) and (conduct\$3	USPAT;	2003/08/13 17:16
		near3 fill\$3) and chip and laser) and 372/\$.ccls.	US-PGPUB;	
			EPO; JPO; DERWENT	
15	32	(/dia poor3 hand\$3) and (apove poor3 rasin) and (apode of \$2)	USPAT;	2003/08/13 17:16
10	ა∠	((die near3 bond\$3) and (epoxy near3 resin) and (conduct\$3		2003/00/13 17:10
		near3 fill\$3) and chip and laser) and 438/\$.ccls.	US-PGPUB; EPO; JPO;	
			DERWENT	
_	15	(die near hand\$3) and (laser near chin) and (anony near regin)	USPAT;	2003/02/26 16:11
-	15	(die near bond\$3) and (laser near chip) and (epoxy near resin)	US-PGPUB	2003/02/26 16:11
			100-56508	